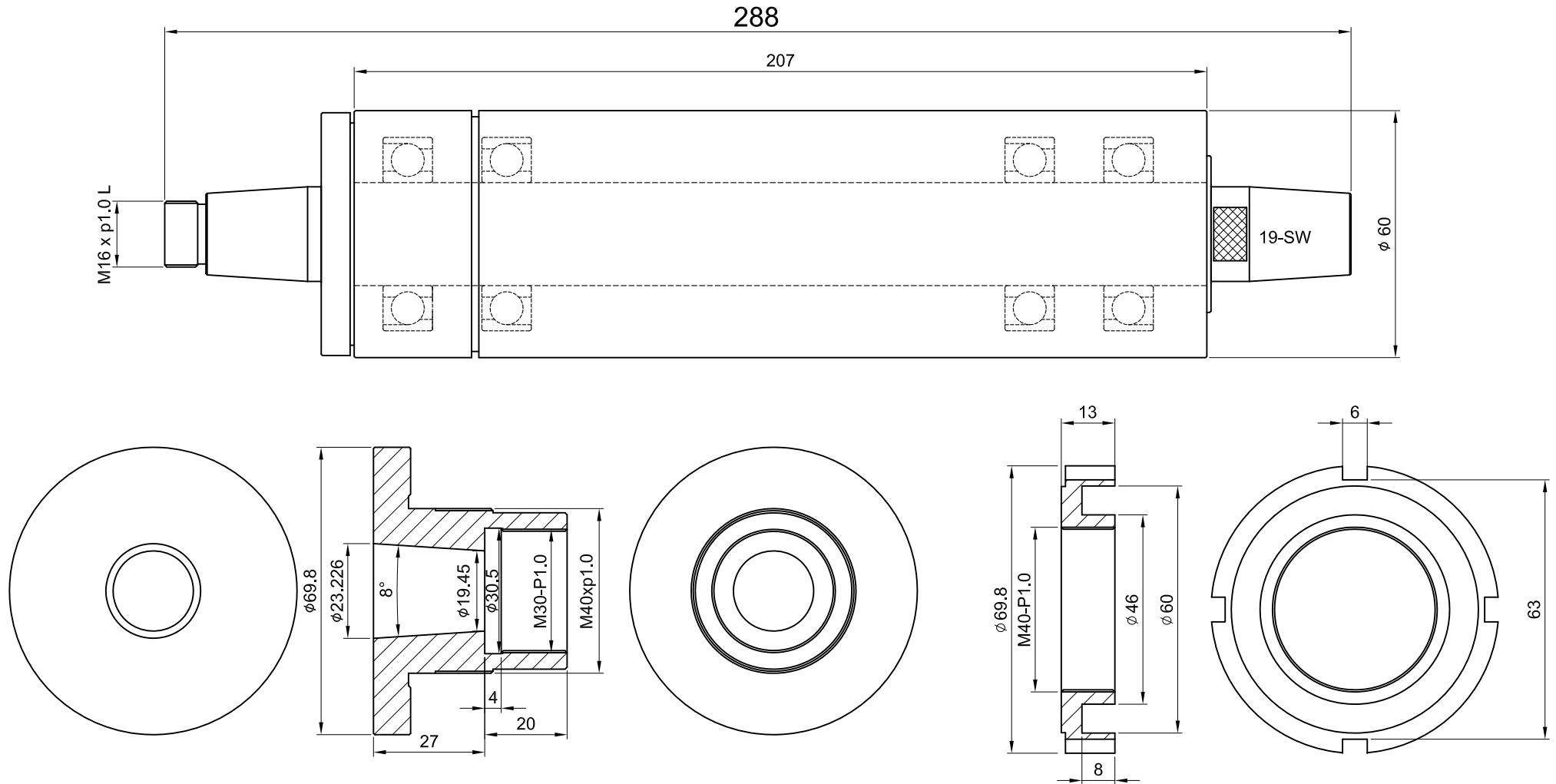


Extremely Precise Wafer Grinding and Cutting Spindle

WGCSP60-20K



Run out : < 0.002 mm

Max. Speed : 20000 rpm

***The manufacturer has the power to change the performance and appearance dimensions.
The change is made to the advanced method of the product.**